

IN THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-5. (Cancelled).

6. (Currently Amended) A method for producing a flip-chip mounting electronic component having a plurality of terminals dotted on a mounting face and a plurality of conductors formed on the terminals, comprising the steps of:

coating the mounting face with a conductor having a predetermined thickness, the coating step including electroless plating followed by electrolytic plating;

masking corresponding positions for the terminal parts on the conductor surface; and removing the conductor except the mask parts, the coating, masking and removing steps being carried out in the stated order.

7-8. (Cancelled).

9. (Currently Amended) A method for producing a circuit board having a plurality of flip-chip mounting lands dotted on a mounting face, comprising the steps of:

coating the mounting face with a conductor having a predetermined thickness, the coating step including electroless plating followed by electrolytic plating;

masking corresponding positions for the lands on the conductor surface; and removing the conductor except the mask parts, the coating, masking and removing steps being carried out in the stated order.

10. (Currently Amended) A method for producing a package in which mounting face terminal parts of a flip-chip mounting electronic component and/or flip-chip mounting lands of a circuit board mounting face have conductors, the conductor made by electroless plating followed by electrolytic plating, the method comprising:

forming the conductors as remaining parts from growing formation and/or removal;
and

securing the conductors of the circuit board and the electronic component or the conductors of the electronic component and the circuit board with solder or anisotropic conductive material.

11. (Previously Presented) The method for producing a package according to claim 10, wherein the conductors are constituted of copper and on surfaces thereof a nickel layer and a gold layer are formed in the stated order, and the securing step is carried out by fixing force of solder.